

L Number	Hits	Search Text	DB	Time stamp
3	1221	(silicon with (mold or mould)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 17:59
6	2510	((mold or mould) and (cap or lid) and semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 17:59
1	4	("4436439" "4372694" "6158907" "5559932").PN.	USPAT; US-PGPUB	2003/10/09 17:59
2	55	(silicon with (mold or mould)) and (semiconductor same cap)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 17:59
4	174	(mold or mould or die) and (semiconductor same caps same wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 17:59
5	1	(wafer with silicon with (mold or mould) with microstructure)	USPAT; US-PGPUB	2003/10/09 17:59
7	25	((mold or mould) and (cap or lid) and semiconductor).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 17:59
8	1	("20020122972").PN.	USPAT; US-PGPUB	2003/10/09 18:15
9	4	((("4436439") or ("4372694") or ("6158907") or ("5559932"))).PN.	USPAT; US-PGPUB	2003/10/09 18:42
10	1645	((249/134) or (249/160) or (249/162)).CCLS.	USPAT; US-PGPUB	2003/10/09 18:56
11	593	((425/408) or (425/416)).CCLS.	USPAT; US-PGPUB	2003/10/09 19:01
12	430	(425/383).CCLS.	USPAT; US-PGPUB	2003/10/09 19:02